

SML1209-0UO-TR

Super Orange
Dome Lens Surface Mount LED
3.2 × 2.4 × 2.5 mm Package
25° viewing angle

DWG BY:
SL / JG
12-06-06

CHK BY:
PL
01-17-07

QA:

__-__-__

MFG:

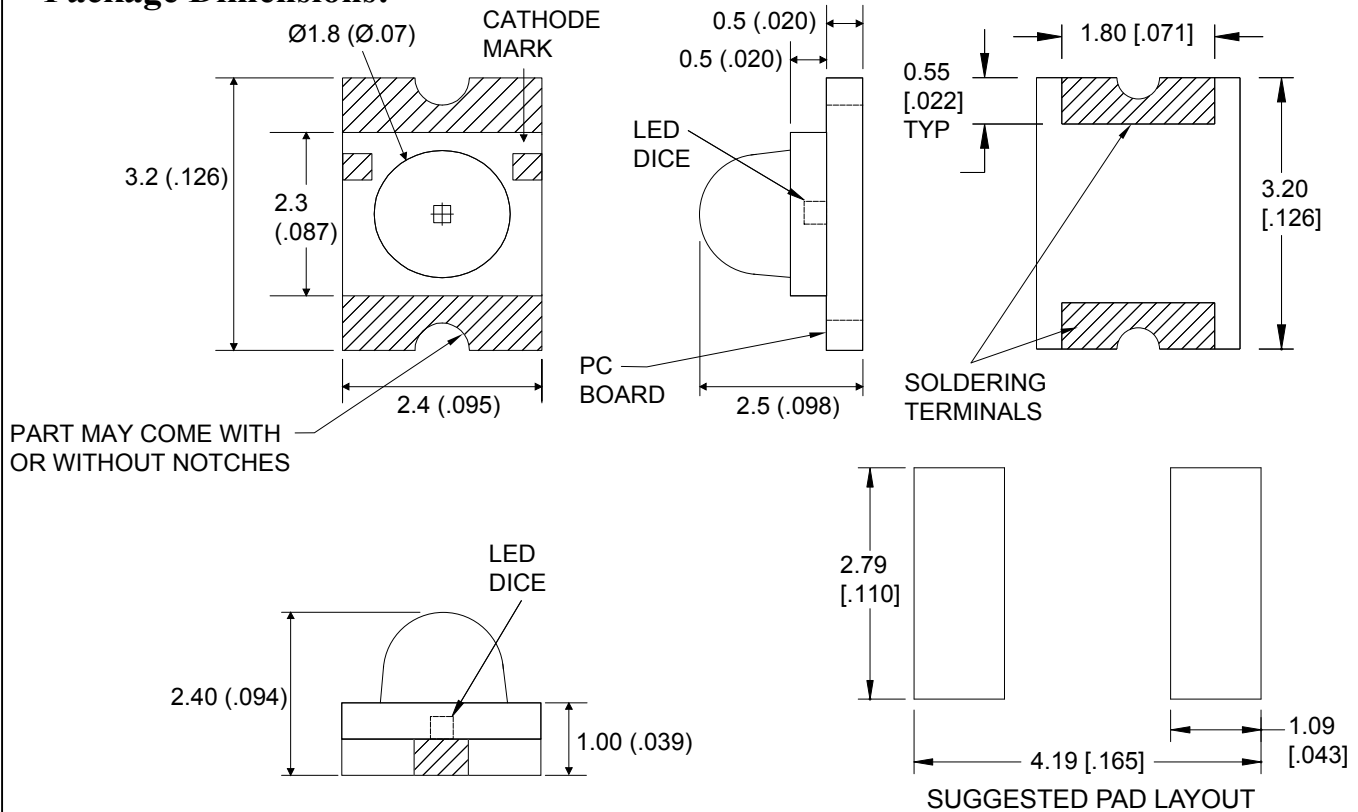
__-__-__

REVISION LTR: -
12-06-06

Features

- * Meet ROHS standards.
- * Dome lens Chip LED.
- * Ultra bright AlInGaP Chip LED.
- * Package in 8mm tape on 7" diameter reels.
- * Compatible with automatic placement equipment.
- * Compatible with infrared and vapor phase reflow solder process.
- * EIA STD package.
- * I.C. compatible.

Package Dimensions:



Part No.	Chip Material	Lens Color	Emission Color
SML1209-0UO-TR	GaAlInP	Water Clear	Super Orange

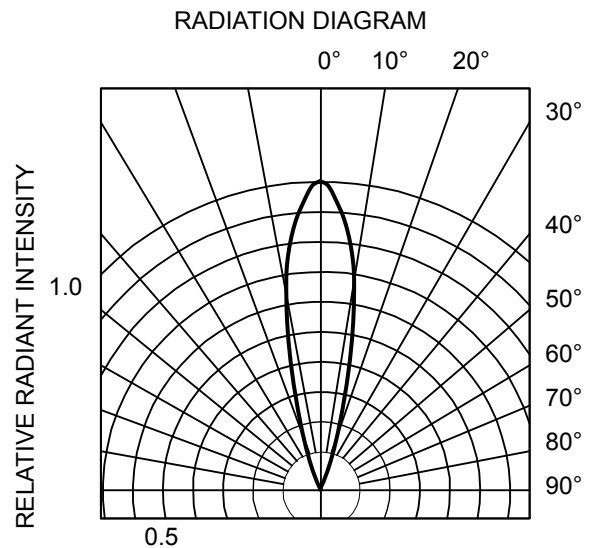
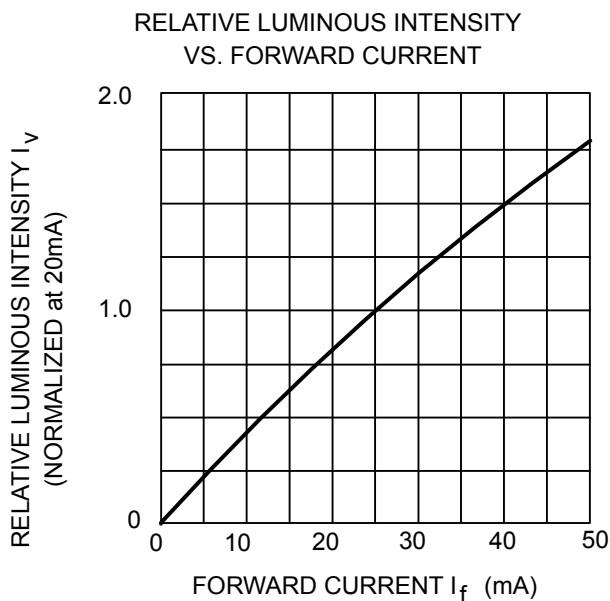
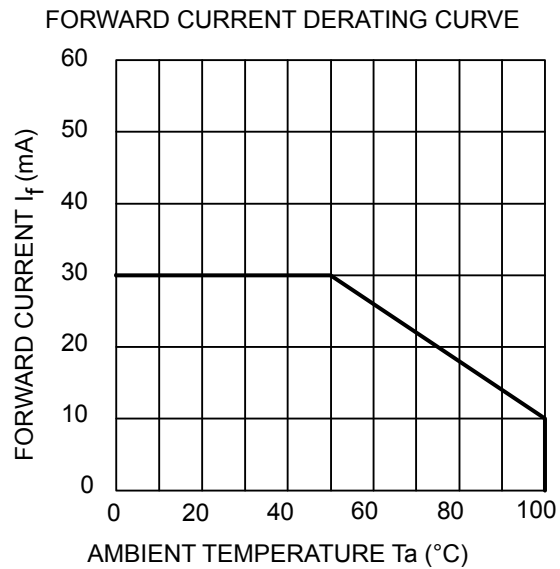
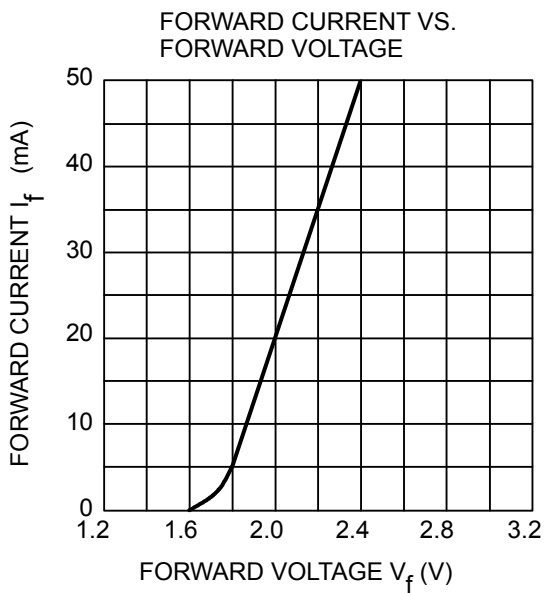
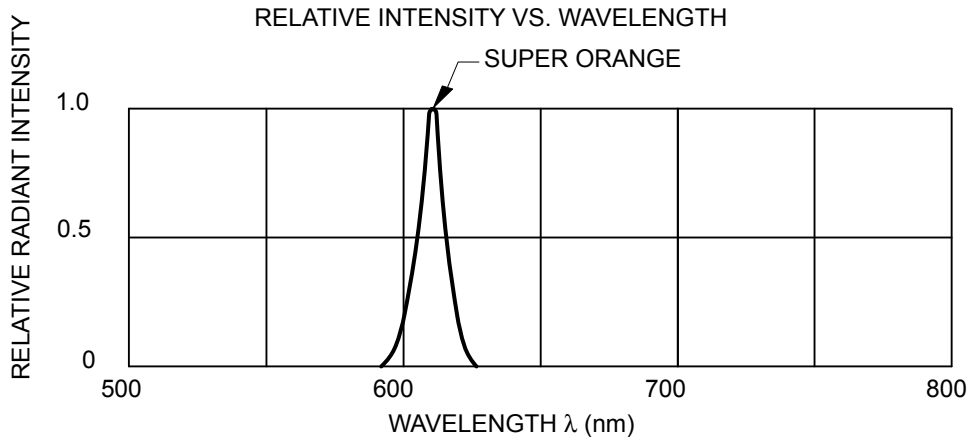
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.1mm (.004") unless otherwise noted.
3. Specifications are subject to change without notice.
4. Precautions for ESD:
 Static electricity and surge can damage the LED. It is recommended to use a wristband or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

Absolute Maximum Ratings (T _A =25°C)			
Parameter	Symbol	Value	Unit
Forward current	I _f	30	mA
Reverse voltage	V _r	5	V
Power dissipation	P _d	75	mW
Operating temperature range	T _{opr}	-55 ~+85	°C
Storage temperature range	T _{stg}	-40 ~+85	°C
Peak forward current (1/10 Duty Cycle, 0.1ms Pulse Width)	I _{fp}	80	mA

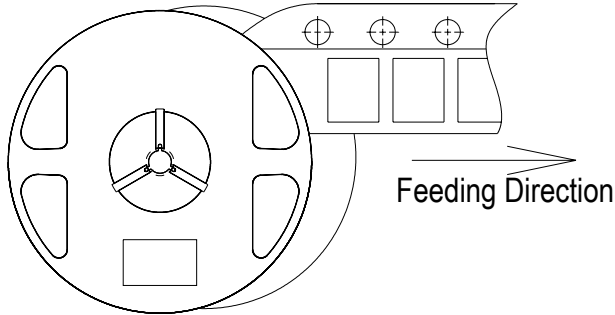
Electro-optical characteristics (T _A =25°C)						
Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
Wavelength at peak emission	I _f =20mA	λ peak	612	613	619	nm
Spectral half bandwidth	I _f =20mA	Δ λ	--	18	--	nm
Dominant wavelength	I _f =20mA	λ dom	605	607	609	nm
Forward voltage	I _f =20mA	V _f	--	2.0	2.6	V
Luminous intensity	I _f =20mA	I _v	--	3000	--	mcd
Viewing angle at 50% I _v	I _f =20mA	2θ _{1/2}	--	25	--	Deg
Reverse current	V _r =5V	I _r	--	--	100	μA
Chromaticity Coordinates	I _f =20mA	X	--	0.65	--	
		Y		0.34		
Radiant Intensity	I _f =20mA	I _e	--	7000	--	μW/sr

OPTICAL CHARACTERISTIC CURVES

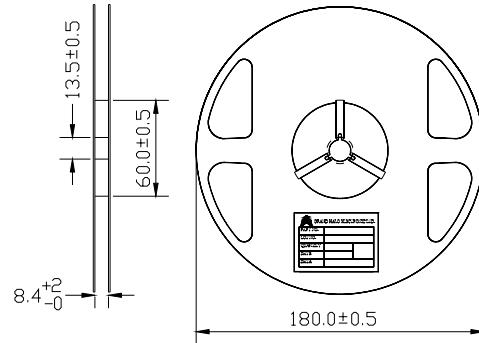


SMD Chip LED Lamps Packaging Specifications

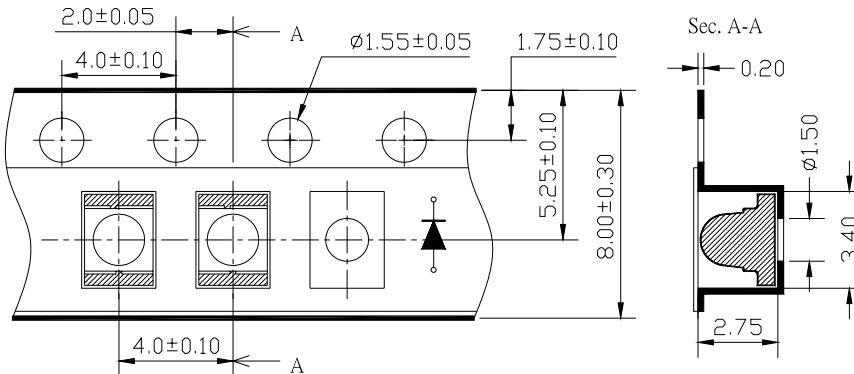
● Feeding



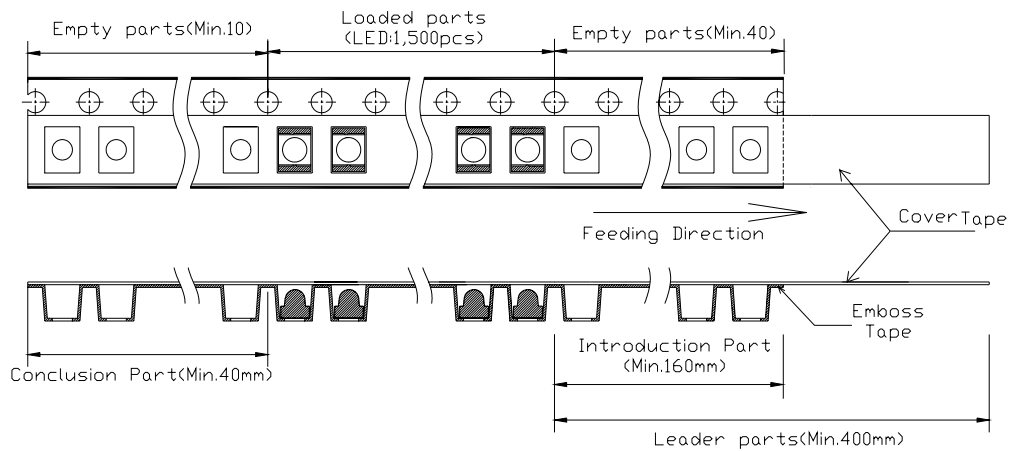
● Dimensions of Reel (Unit: mm)



● Dimensions of Tape (Unit: mm)



● Arrangement of Tape



NOTES

1. Empty component pockets are sealed with top cover tape;
2. The maximum number of missing lamps is two;
3. The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications.
4. 1,500 pcs/Reel

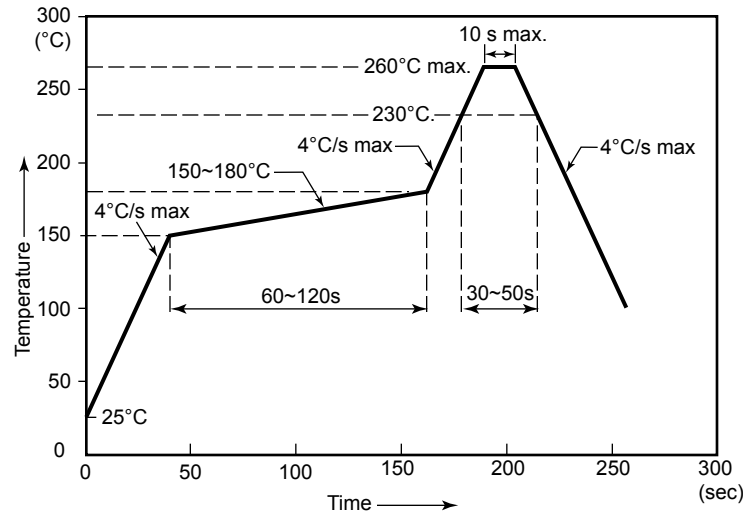


Test items and results of reliability

Type	Test Item	Test Conditions	Note	Number of Damaged
Environmental Sequence	Temperature Cycle	-20°C 30min ↑ ↓ 80°C 30min	100 cycle	0/22
	Thermal Shock	-20°C 15min ↑ ↓ 80°C 15min	100 cycle	0/22
	High Humidity Heat Cycle	30°C ↔ 65°C 90%RH 24hrs/1cycle	10 cycle	0/22
	High Temperature Storage	T _a =80°C	1000 hrs	0/22
	Humidity Heat Storage	T _a =60°C RH=90%	1000 hrs	0/22
	Low Temperature Storage	T _a =-30°C	1000 hrs	0/22
Operation Sequence	Life Test	T _a =25°C I _F =20mA	1000 hrs	0/22
	High Humidity Heat Life Test	60°C RH=90% I _F =10mA	500 hrs	0/22
	Low Temperature Life Test	T _a =-20°C I _F =20mA	1000 hrs	0/22

Reflow Profile

■ Reflow Temp/Time



NOTES:

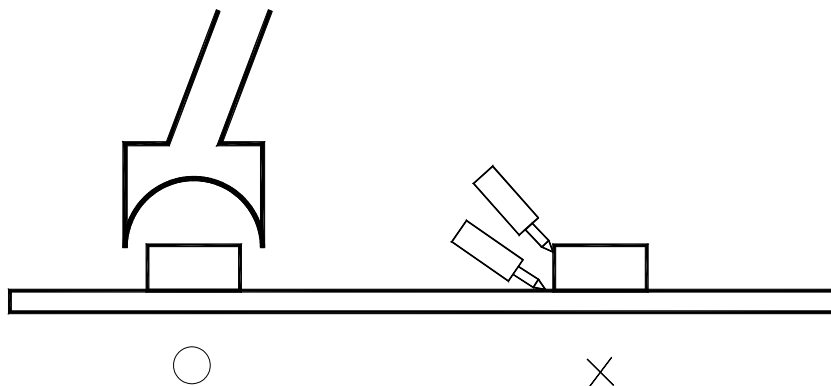
1. We recommend the reflow temperature at 245°C (±5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

■ Soldering iron

Basic spec is ≤ 5sec when 260°C. If temperature is higher, time should be shorter (+10°C → -1sec). Power dissipation of iron should be smaller than 15W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

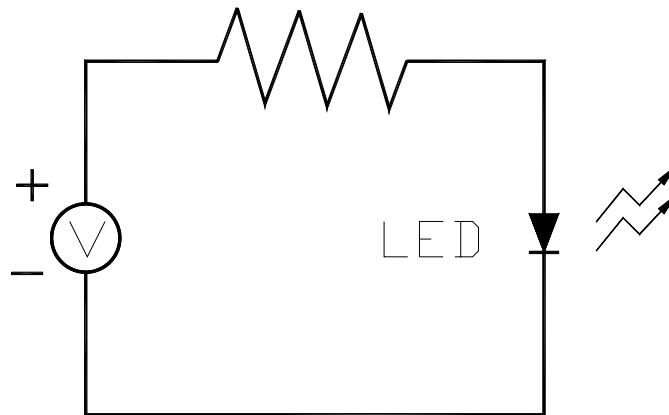
■ Rework

1. Customer must finish rework within 5 sec under 260°C.
2. The head of iron cannot touch copper foil.
3. Twin-head type is preferred.



Test circuit and handling precautions

■ Test circuit



■ Handling precautions

1. Over-current-proof

Customer must apply resistors for protection; otherwise a slight voltage shift will cause a big change in current (Burn out occurs).

2.Storage

2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature : 5°C~30°C (41°F~86°F)

2.2 Shelf life in sealed bag: 12 months at < 5°C~30°C and < 30% R.H. after the package is opened, the products should be used within a week or they should be kept stored at \leq 20 R.H. with zip-lock seal.

3.Baking

It is recommended to bake before soldering when the pack is unsealed after 72hrs.

The conditions are as follows:

3.1 60±3°C x(12~24hrs) and < 5%RH, taped reel type

3.2 100±3°C x(45min~1hr), bulk type

3.3 130±3°C x(15~30min), bulk type